



## Triple Ion-Beam Cutter for Easy Site Specific Sample Preparation

### Leica EM TIC020

- Mills at high rates (120  $\mu\text{m}/\text{h}$  for Si), cuts broad and deep, creates smooth surfaces (Ebsd)
- Prepares up to 50 x 50 x 10 mm large samples
- Simple operation via touch screen, no special skills necessary
- Quick and easy access for maintainance

Living up to Life